

Docket No.: 27604-00003-US1
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Hiroyuki Sakamoto et al.

Application No.: 10/528,153

Confirmation No.: 2814

Filed: August 19, 2005

Art Unit: 1795

For: METHOD OF ADHESION OF CONDUCTIVE
MATERIALS, LAMINATE, AND ADHESIVE
COMPOSITION

Examiner: TAI, Xiuyu

SUPPLEMENTAL RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

This is in a supplemental response to the Office Action dated August 5, 2008.

No Amendments to the Claims have been made in this paper.

Remarks/Arguments begin on page 2 of this paper.